

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No. : Unassigned  
Applicant : Carapella, et al.  
Filed : 09/08/2003  
Title : METHODS OF SPLIT CAVITY WALL PLATING FOR  
AN INTEGRATED CIRCUIT PACKAGE (As Amended)

Docket No. : 42P6139CD  
Customer No. : 8791

---

Which is a Divisional of:

Appl. No. : 09/665,034  
Applicant : Carapella, et al.  
Filed : 09/19/2000  
Title : METHODS FORMING AN INTEGRATED CIRCUIT  
PACKAGE WITH A SPLIT WALL (As Amended)  
TC/A.U. : 3729  
Examiner : Chang, Rick Kiltae

---

Which is a Continuation of:

Appl. No. : 09/153,630  
Applicant : Carapella, et al.  
Filed : 09/15/1998  
Title : SPLIT CAVITY WALL PLATING FOR AN  
INTEGRATED CIRCUIT PACKAGE

**PRELIMINARY AMENDMENT ACCOMPANYING**  
**35 USC 120 and 37 CFR 1.53(b)(1) DIVISIONAL APPLICATION**

Mail Stop New Application  
Commissioner for Patents  
Alexandria, VA 22313

Dear Sir:

Prior to a first examination in the 35 USC 120 and 37 CFR 1.53(b)(1) divisional application filed herewith, please enter the following amendments:

**Title Amendments** begin on page 2.  
**Specification Amendments** begin on page 3.  
**Drawing Amendments** begin on page 6.  
**Claim Amendments** begin on page 7.  
**Remarks** begin on page 15.  
**Conclusion** with signature is on page 21.

IN THE TITLE

Please amend the Title of the Application as follows:

"METHODS OF SPLIT CAVITY WALL PLATING FOR AN INTEGRATED  
CIRCUIT PACKAGE".